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PLEASE AMEND THE ABSTRACT AS FOLLOWS:

ABSTRACT

A metal interconnect structure featuring a metal ring component located entirely in a via hole opening, and attached to an adjacent planar metal structure component, has been developed. The planar metal structure component is located on a smooth top surface of an underlying insulator layer, while the metal ring component is located entirely in a top portion of a via hole opening which in turn was defined in the insulator layer, with the via hole opening exposing the top surface of a recessed metal plug structure. The metal ring component, attached to only one side of the planar metal structure component, is comprised of metal spacers located on the sides of the via hole opening, with the metal spacers also overlying portions of the recessed metal plug structure located at the bottom of the via hole opening. The space between metal spacers allows exposure of an uncovered portion of the recessed metal plug structure.